

pitch UCSP™.

EVALUATION KIT AVAILABLE



## **RF Power Detector** with Shutdown Control

#### Features

- ✤ -25dBm to -5dBm Power Detection Range
- ±0.5dB Detection Error Due to Temperature
- + +2.7V to +5V Single-Supply Operation
- ♦ Space-Saving 4-Bump, 1mm<sup>2</sup> UCSP Package
- Shutdown Control
- 140ns Step-Response Time

MAX2209A

### Applications

**General Description** 

Dual-Band WCDMA Handsets High-Speed Downlink Packet Access (HSDPA) High-Speed Uplink Packet Access (HSUPA)

The MAX2209A is a wideband (800MHz to 2GHz) RF

power detector. It takes an RF signal from the directional

coupler at the input, and outputs a DC voltage propor-

tional to the RF peak voltage. The change in output

voltage versus temperature is very repeatable from part to part and enables a lookup table based on nominal

behavior, minimizing the effective detection error to less

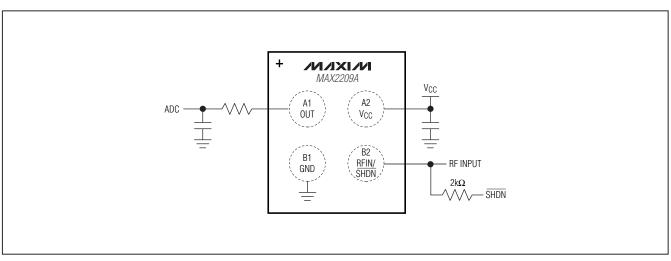
The MAX2209A comes in a space-saving 2 x 2, 0.5mm

than ±0.5dB relative to room temperature.

### **Ordering Information**

PART	TEMP RANGE	PIN- PACKAGE	TOP MARK	
MAX2209AEBS+	-40°C to +85°C	4 UCSP	AGJ	

+Denotes a lead(Pb)-free/RoHS-compliant package.



### Functional Diagram/Typical Operating Circuit

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For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

#### **ABSOLUTE MAXIMUM RATINGS**

VCC to GND	-0.3V to +6V
RFIN to GND	
OUT to GND	
RFIN Input Power	· · · · /
Continuous Power Dissipation (	
Continuous i ower Dissipation (	TA = TTO O

4-Bump WLP (derate 3mW/°C above +70°C)......238mW

Junction-to-Ambient Thermal	
Resistance (0JA) (Note 1)	335°C/W
Operating Temperature Range	40°C to +85°C
Storage Temperature Range	65°C to +160°C
Junction Temperature	+150°C
Bump Temperature (soldering, Note 2)	
Infrared (15s)	+260°C
Soldering Temperature (reflow)	+240°C

Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a 4-layer board. For detailed information on package thermal considerations, refer to <u>www.maxim-ic.com/thermal-tutorial</u>.
Note 2: For detailed information on soldering, refer to Application Note 1891: Wafer-Level Packaging (WLP) and Its Applications.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

CAUTION! ESD SENSITIVE DEVICE

#### **DC ELECTRICAL CHARACTERISTICS**

(V<sub>CC</sub> = 2.7V to 5.0V, no RF signal applied,  $T_A = -40^{\circ}$ C to +85°C. Typical values are at V<sub>CC</sub> = 2.8V,  $T_A = +25^{\circ}$ C, unless otherwise noted.) (Note 3)

PARAMETER CONDITIONS		MIN	TYP	MAX	UNITS
Supply Voltage		2.7		5.0	V
Supply Current			3.9	6	mA
Idle Output Voltage			35		mV
Output Current Source Capability	P <sub>IN</sub> = -5dBm, V <sub>OUT</sub> forced 100mV lower than open- circuit output voltage	1000	2300		μA
Output Current Sink Capability	P <sub>IN</sub> = -25dBm, V <sub>OUT</sub> forced 10mV higher than open- circuit output voltage	75	150		μA
Shutdown Current	VSHDN = 0V		25	50	μA
SHDN Logic-High	$V_{IH}$ , including 2k $\Omega$ resistor	1.2			V
SHDN Logic-Low	$V_{IL}$ , including 2k $\Omega$ resistor			0.45	V
Turn-On Time SHDN transitions to VIH, VOUT is within 90% of final value (Note 4)			1.5	2	μs
RF Step-Response Time	sponse Time RF transitions from < -25dBm to -5dBm, V <sub>OUT</sub> is within 90% of final value, $1k\Omega + 10pF$ load (Note 4)		140	200	ns

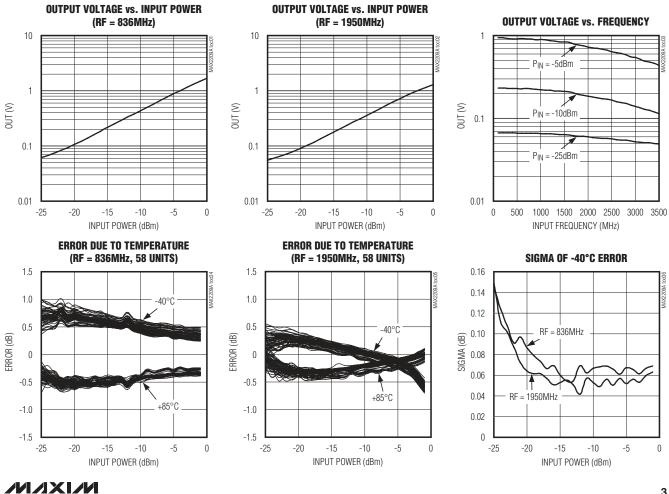
### **AC ELECTRICAL CHARACTERISTICS**

(V<sub>CC</sub> = 2.8V. Typical values are at  $T_A$  = +25°C, unless otherwise noted.)

 $(50\Omega \text{ system}, \text{V}_{\text{CC}} = 2.8\text{V}, \text{T}_{\text{A}} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}.$  Typical values are at TA = +25°C, unless otherwise noted.) (Note 3)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	
RF Input Frequency		800		2000	MHz	
	800MHz		16			
RF Input Return Loss	2000MHz		9		dB	
0.1.1.1/1	-5dBm input		0.88		V	
Output Voltage, 836MHz	-25dBm input		0.06			
Output Valtage 1050ML	-5dBm input		0.72		V	
Output Voltage, 1950MHz	-25dBm input		0.06			
Residual Error after Room	-5dBm input			±0.5	- dB	
Temperature Calibration (T <sub>A</sub> = -40°C to +85°C) (Note 4)	-25dBm input			±1.5		

**Note 3:** Guaranteed by production test at  $T_A = +25^{\circ}C$ . Guaranteed by design and characterization at  $T_A = -40^{\circ}C$  and  $T_A = +85^{\circ}C$ . Note 4: Guaranteed by design and characterization. See the Typical Operating Characteristics.

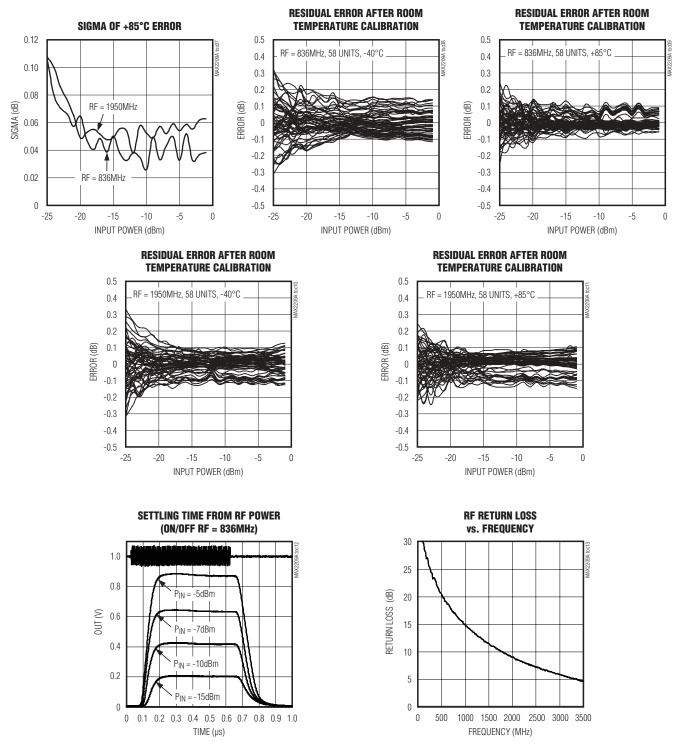


**Typical Operating Characteristics** 

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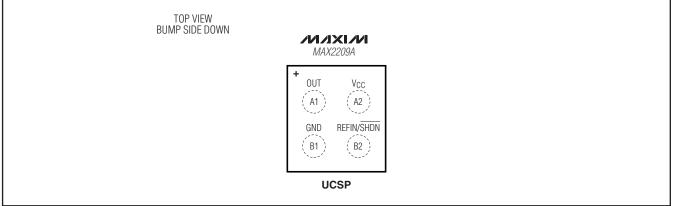
**Typical Operating Characteristics (continued)** 

(V<sub>CC</sub> = 2.8V. Typical values are at  $T_A$  = +25°C, unless otherwise noted.)



**MAX2209A** 

## Bump Configuration



## **Bump Description**

BUMP	NAME	FUNCTION		
A1 OUT Detector Output				
A2 V <sub>CC</sub> Power Supply. Bypass to GND with a capacitor as close as possible to the bump.				
B1 GND Ground Connection. Connect to PCB ground plane with as low inductance as possible.		Ground Connection. Connect to PCB ground plane with as low inductance as possible.		
B2 RFIN/SHDN RF Input and Shutdown Control. AC-couple the RF input and DC couple the shutdown of through a 2kΩ resistor to this pin.		RF Input and Shutdown Control. AC-couple the RF input and DC couple the shutdown control through a $2k\Omega$ resistor to this pin.		

### **Detailed Description**

The MAX2209A power detector is designed to operate from 800MHz to 2.0GHz. The device is ideal for wideband code-division multiple access (WCDMA), cdma2000<sup>®</sup>, and high-speed downlink/uplink packet access. The MAX2209A accepts an RF signal at the input, and outputs a temperature-independent voltage related to the input signal power. The output voltage expressed in dBV is proportional to the input power expressed in dBM. The device has a detection range from -25dBm to 0dBm.

#### **Applications Information**

The typical application circuit, as taken from the MAX2209A EV Kit, is shown in Figure 1. The IC can be shut down by forcing the RFIN/SHDN DC voltage low through a  $2k\Omega$  resistor. The output of the detector goes to an ADC for further processing by the baseband system. Connect a series resistor and shunt capacitor to the MAX2209A output to reduce residual amplitude ripple. The series resistor should not be less than  $1k\Omega$ .

EV kit gerber files, schematic, BOM, and updates are available on the MAX2209A product page at Maxim's website (<u>www.maxim-ic.com</u>).

There are two areas that require attention: the GND pin and the supply bypassing. Connect the GND pin to the PCB ground with a GND via as close as possible, and bypass V<sub>CC</sub> to ground with a capacitor as close as possible to the part.

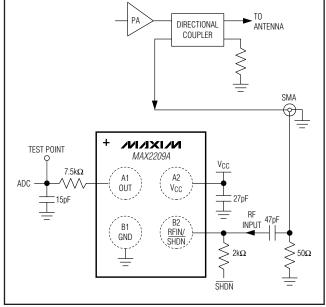


Figure 1. Typical Application Circuit from MAX2209A EV Kit

#### **Chip Information**

PROCESS: BIPOLAR

Lavout

#### **Package Information**

For the latest package outline information and land patterns, go to **www.maxim-ic.com/packages**. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE	PACKAGE	OUTLINE	LAND
TYPE	CODE	NO.	PATTERN NO.
4 UCSP	B4+4	<u>21-0007</u>	

cdma2000 is a registered trademark of the Telecommunications Industry Association.

### **Revision History**

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	9/10	Initial release	

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

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